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(57) Abstract :
A substrate holder system (100) for cladding, features a cuboidal shaped holder (101) designed to securely support a substrate material (104). At the top of the holder, a cavity (102) is integrated with walls (103) configured to contain and manage susceptor material (106), which continuously supplies heat to the substrate, ensuring uniform deposition of the cladding layer. The walls (103) are specifically structured to contain heat, reducing fire risks within the dielectric chamber (105) during the cladding process. The system (100) includes an integrated temperature probe (109) within the cavity (102) to monitor and control temperature. Additionally, a separator plate (108) is positioned inside the holder, situated between the susceptor material (106) and the cladding material (107). This plate facilitates efficient heat transfer from the susceptor to the cladding while preventing contamination. This design ensures consistent cladding quality and safety by maintaining precise temperature control and preventing heat-related hazards.

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